

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Seong-Joon Lee</td> <td>08/21/2012</td> </tr> <tr> <td>Ki-Sik Pak</td> <td>08/21/2012</td> </tr> </tbody> </table>		Name	Execution Date	Seong-Joon Lee	08/21/2012	Ki-Sik Pak	08/21/2012
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Seong-Joon Lee	08/21/2012						
Ki-Sik Pak	08/21/2012						
RECEIVING PARTY DATA							
Name:	Samsung SDI Co., Ltd.						
Street Address:	428-5, Gongse-dong, Giheung-gu						
City:	Yongin-si, Gyeonggi-do						
State/Country:	KOREA, REPUBLIC OF						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13605127</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13605127		
Property Type	Number						
Application Number:	13605127						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	Michael H. Trenholm						
Total Attachments: 1 source=SDISHN277 ASSIGN#page1.tif							

OP \$40.00 13605127

Application No.: Unknown
 Filing Date: Herewith

Client Code: SDISHN.277AUS
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ASSIGNMENT

WHEREAS, I, the undersigned, have invented certain new and useful improvements in a **BATTERY PACK**, the specification of which was executed on even date herewith.

AND WHEREAS, **Samsung SDI Co., Ltd.**, (hereinafter "ASSIGNEE"), with its principal place of business at **428-5, Gongse-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea**, desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, in light of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Date: August 21, 2012

Signature: LEE Seong-Joon

Name: LEE, Seong-Joon

Address: c/o Samsung SDI Co., Ltd.
428-5, Gongse-dong, Giheung-gu, Yongin-si,
Gyeonggi-do, Republic of Korea

Date: August 21, 2012

Signature: PAK Ki-Sik

Name: PAK, Ki-Sik

Address: c/o Samsung SDI Co., Ltd.
428-5, Gongse-dong, Giheung-gu, Yongin-si,
Gyeonggi-do, Republic of Korea

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